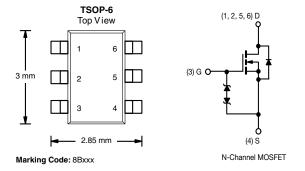


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Vishay Siliconix

# Automotive N-Channel 40 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	40			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.032			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.048			
I <sub>D</sub> (A)	8			
Configuration	Single			



### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Typical ESD Protection 800 V
- AEC-Q101 Qualifiedd
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and Halogen-free	SQ3418EEV-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	40		
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	1	8		
	T <sub>C</sub> = 125 °C	l <sub>D</sub>	5		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	6	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	32		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	5		
Single Pulse Avalanche Energy	L = 0.1 min	E <sub>AS</sub>	1.2	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	$P_{D}$	5	W	
	T <sub>C</sub> = 125 °C		1.6	VV	
Operating Junction and Storage Temperatur	e Range	T <sub>J</sub> , T <sub>stq</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient PC	CB Mount <sup>c</sup>	R <sub>thJA</sub>	110	°C/W	
Junction-to-Foot (Drain)		R <sub>thJF</sub>	30	C/VV	

## Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static				l		l .		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		40		-	V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	\ \	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$		-	-	± 500	nA	
		V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 1	mA	
Zero Gate Voltage Drain Current		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V	-	-	1		
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 125 °C	-	-	50	μА	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 175 °C	=.		150		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	10	-	-	Α	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 5 A	-	0.026	0.032	Ω	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 5 A, T <sub>J</sub> = 125 °C	-	-	0.050		
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 5 A, T <sub>J</sub> = 175 °C	-	-	0.061		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 4 A	-	0.040	0.048		
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4 A		=.	13	-	S	
Dynamic <sup>b</sup>	<u> </u>							
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	528	660	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		=.	112	140		
Reverse Transfer Capacitance	C <sub>rss</sub>	]		-	76	95		
Total Gate Charge <sup>c</sup>	Qg	V <sub>GS</sub> = 4.5 V	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 4 A	-	7.1	11	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			-	1.7	-		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	]		=.	3.7	-		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.2	2.4	3.6	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	8	12		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, \text{ R}_L = 4 \Omega$ $I_D \cong 5 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		-	8	12	- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	15	23		
Fall Time <sup>c</sup>	t <sub>f</sub>			-	7	11		
Source-Drain Diode Ratings and Chara	acteristics T <sub>C</sub> = 2	25 °Cb						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	32	Α	
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0		-	0.8	1.2	V	

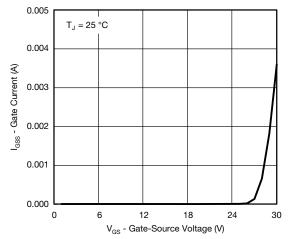
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

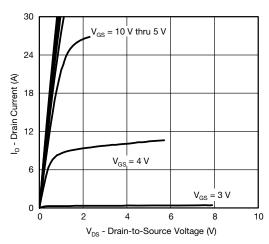
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



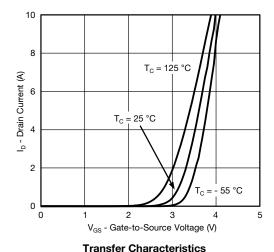
## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)

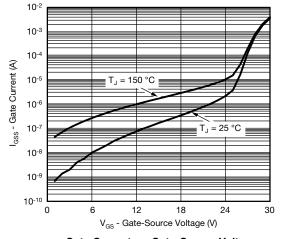


#### Gate Current vs. Gate-Source Voltage

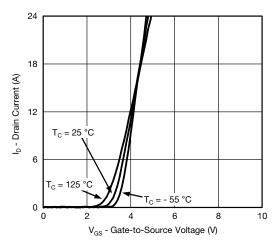


#### **Output Characteristics**

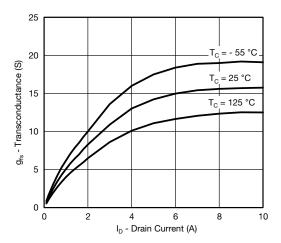




Gate Current vs. Gate-Source Voltage



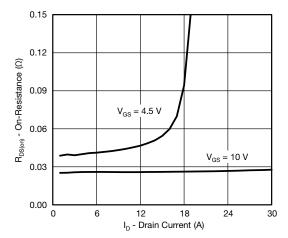
Transfer Characteristics



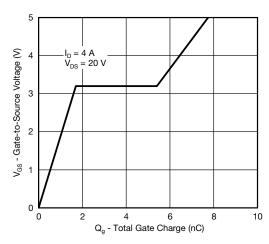
Transconductance



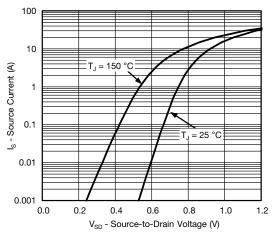
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



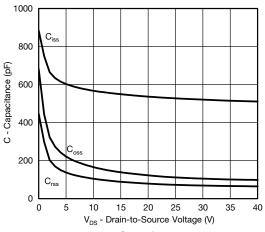
#### On-Resistance vs. Drain Current



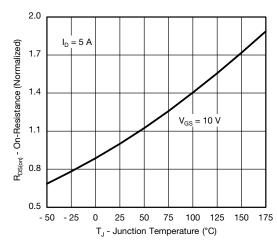
#### **Gate Charge**



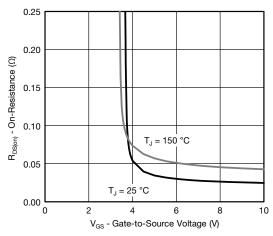
Source-Drain Diode Forward Voltage



Capacitance



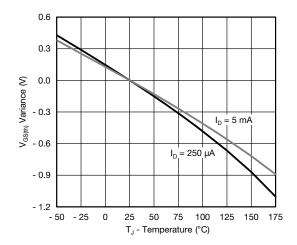
On-Resistance vs. Junction Temperature



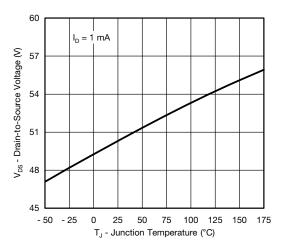
On-Resistance vs. Gate-Source Voltage



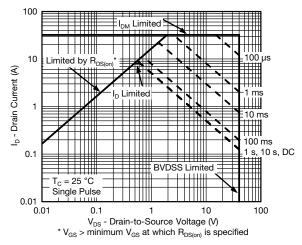
## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)







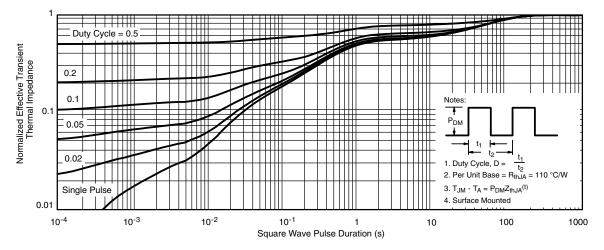
**Drain-Source Breakdown vs. Junction Temperature** 



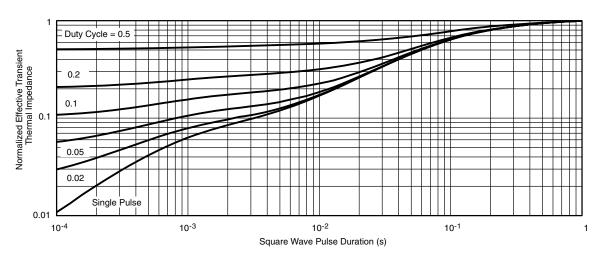
Safe Operating Area

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## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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